RELIABILITY TEST DATA

Product Name: FA-128 (40 MHz < fo \le 54 MHz)

The Company evaluation condition

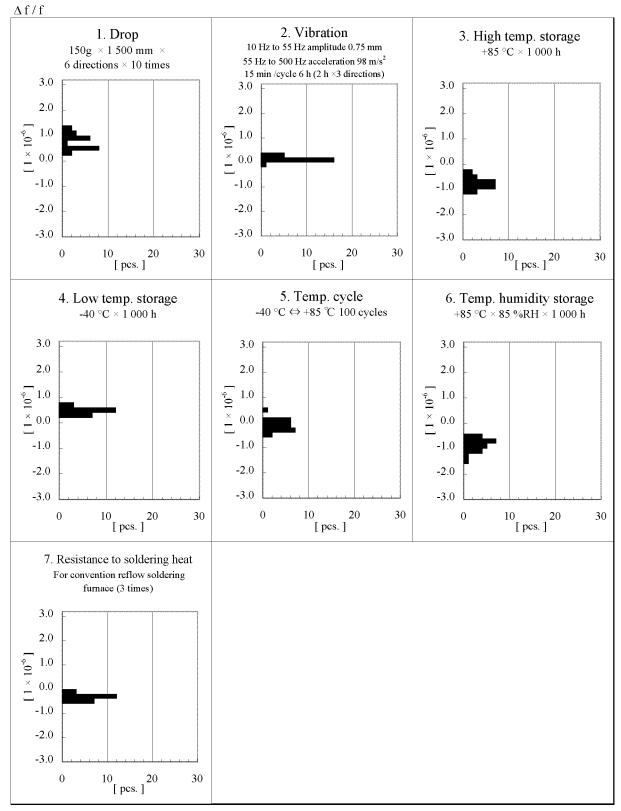
We evaluate environmental and mechanical characteristics by the following test condition.

		and mechanical characteristics by the following	VALUE *1 *2	TEST	FAIL
No.	ITEM	TEST CONDITIONS	Δ f / f	Qty	Qty
			$[1 \times 10^{-6}]$	[n]	[n]
1	Drop	150g dummy Jig (Epsontoyocom Standard) drop from 1500 mm height on the Concrete 6 directions 10 times	*3 ± 3	22	0
2	Vibration	10 Hz to 55 Hz amplitude 0.75 mm 55 Hz to 500 Hz acceleration 98 m/s ² 10 Hz \rightarrow 500 Hz \rightarrow 10 Hz 15 min / cycle 6 h (2 h × 3 directions)	*3 ± 3	22	0
3	High temperature storage	+85 °C × 1 000 h	*3 ± 3	22	0
4	Low temperature storage	-40 °C × 1 000 h	*3 ± 3	22	0
5	Temperature cycle	-40 °C ⇔ + 85 °C 30 min at each temp. 100 cycles	*3 ± 3	22	0
6	Temperature humidity storage	+85 °C × 85 %RH × 1 000 h	*3 ± 3	22	0
7	Resistance to soldering heat	For convention reflow soldering furnace (3 times)	± 2	22	0
8	Substrate bending	Bend width reaches 3.0 mm and hold for $5 \text{ s} \pm 1 \text{ s} \times 1$ time Ref. IEC 60068-2-21	No peeling - off at a solder part	11	0
9	Shear	10 N press for 10 s ± 1 s Ref. IEC 60068-2-21	No peeling - off at a solder part	11	0
10	Pull - off	10 N press for 10 s ± 1 s Ref. IEC 60068-2-21	No peeling - off at a solder part	11	0
11	Solderability	Dip termination into solder bath at +235°C ± 10 °C for 5 s (Using Rosin Flux)	Termination must be 95 % covered with fresh solder	11	0

Notes

- 1. *1 Each test done independently.
- 2. *2 Measuring 2 h to 24 h later leaving in room temperature after each test.
- 3. *3 Measuring 24 h later leaving in room temperature after each test.
 - 1. Reflow 3 times
 - 2. Initial value shall be after 24h at room temperature.
- 4. Shift series resistance at before above tests should be less than ± 20 % or less than ± 10 Ω .

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